WinWay

TWSE 6515

Investor Presentation

● ● ● ● ● 2024.12.10

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Safe Harbor Notice

This presentation may contain forward-looking statements. All statements, other than statements of historical facts, that address activities, events or developments that WinWay Technology Co., Ltd. expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates and business plans) are forward-looking statements.

WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

This presentation does not undertake any obligation to publicly update any forward-looking statements to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Company Information

- **Founded**

  2001 / 4 / 10

- **Business Operation**

  Design, manufacture, sale and service of test interface products

- **Chairman & CEO**

  Mark Wang

- **Capital Stock**

  NTD 350,153,320

- **Employees**

  1,001

- **Registered Address**

  No.68, Chuangyi S. Rd, Nanzi Dist.
  Kaohsiung City, Taiwan

Kaohsiung Headquarter

Hsinchu Branch Office

Company Vision

Innovation

We deliver the best possible test tooling solutions to our customers through technological innovation.

Quality

We exceed customers' quality requirements by offering cost-effective total solutions and on-time delivery worldwide.

Service

We strive to become the world's leading professional testing service provider in all phases of IC testing.

Agenda

Global Presence

Industry Trend

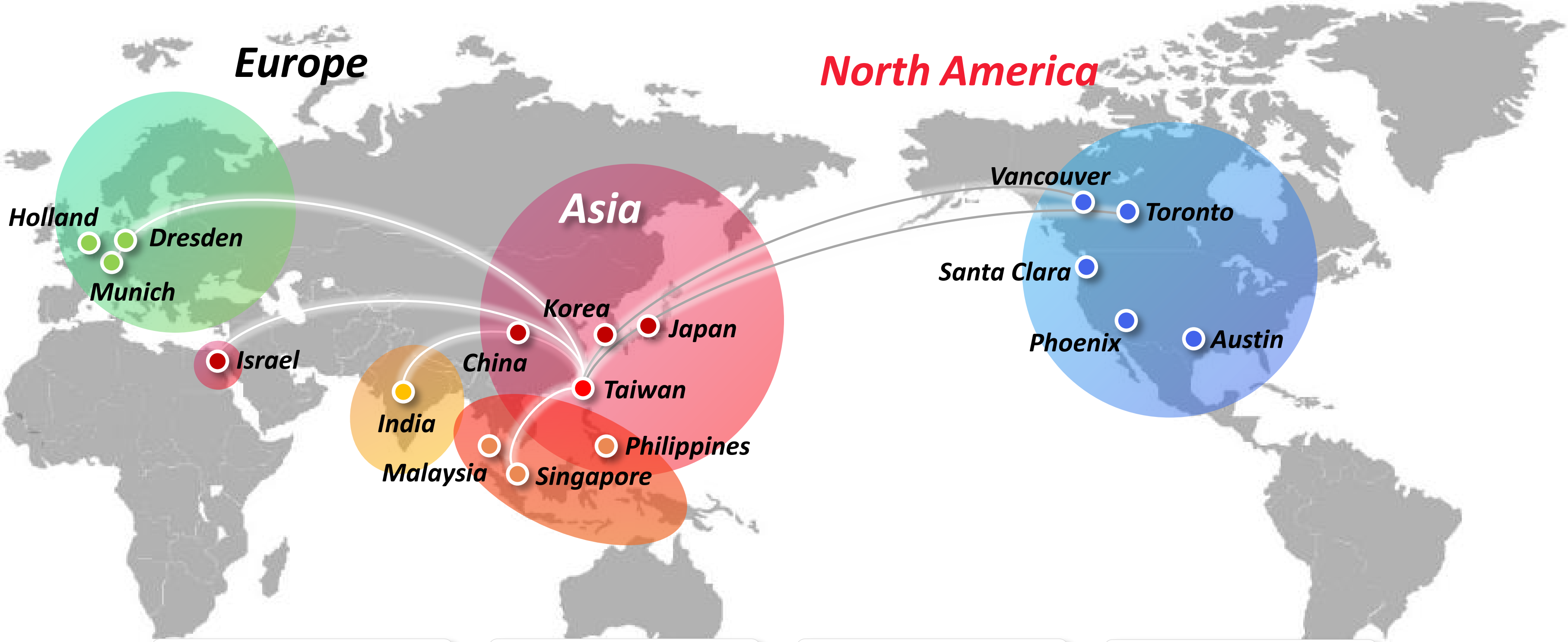
Financial Performance

R&D Innovation

01

Global Presence

Global Service & Support Network



KH Spring Probe

Spring Probe
for Socket

KH Plant

Coaxial Socket
HyperSocket™

Hsinchu Plant

Vertical Probe Card
MEMS Probe Card

Suzhou Plant

Burn-in Socket

Semiconductor Test Interface Leadership

3

2023

Test Socket Ranking

5

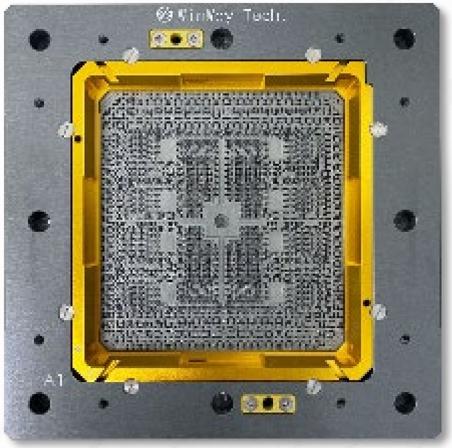
2023

Test and Burn-in Socket Ranking

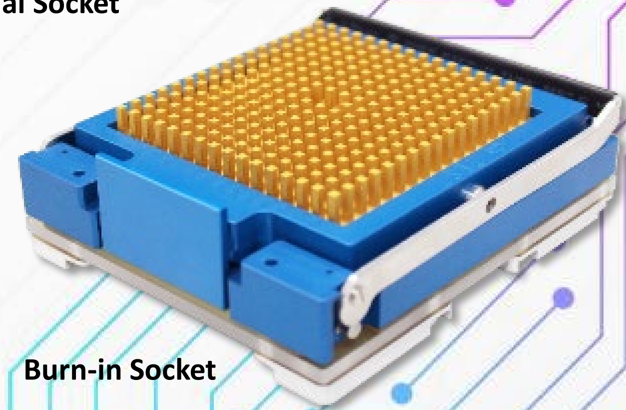
22

2023

Probe Card Ranking



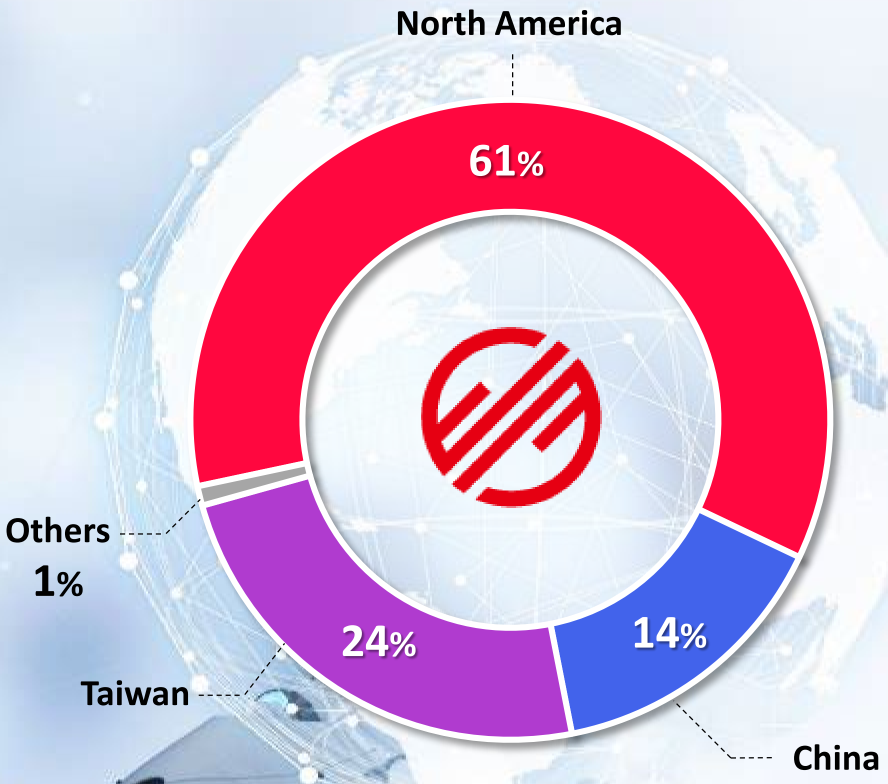
Coaxial Socket



Burn-in Socket

Source: Yole Intelligence, 2024/04

Worldwide Customer



86% **Top10 Customers**

- AI
- AP
- HPC
- CPU
- ASIC
- GPU

200^{+} Active Customers

- 🟥 IC Design
- 🟥 IDM
- 🟥 CSP
- 🟥 OSAT
- 🟥 Foundry

Bolstered by Advanced Technology

(First 9 Months of 2024)

Advanced Node


AI


HPC

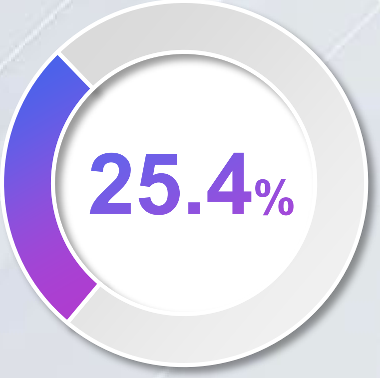

GPU


CPU


Smart Phone

7nm (or equivalent node) and below

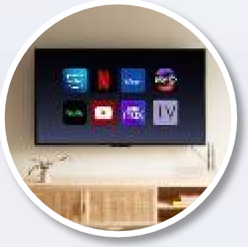
Mature Node




Automotive


Networking


IoT


DTV & STB


NAND Flash

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02

Industry Trend

AI Semiconductor Mega-Trend

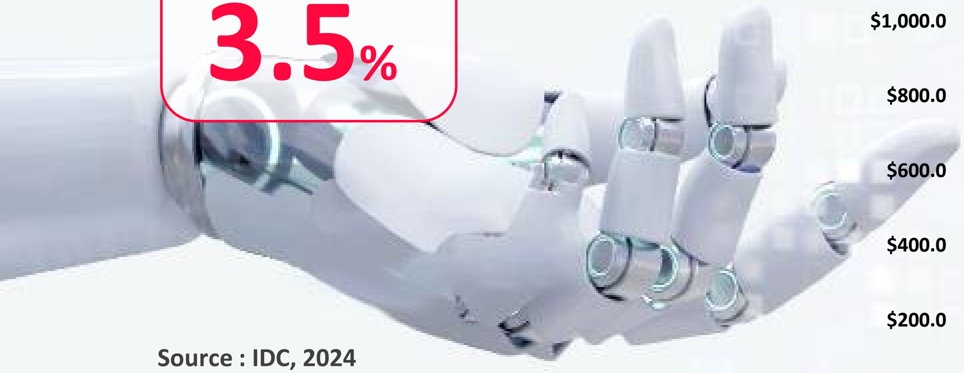
Global AI Economic Impact

$19.9

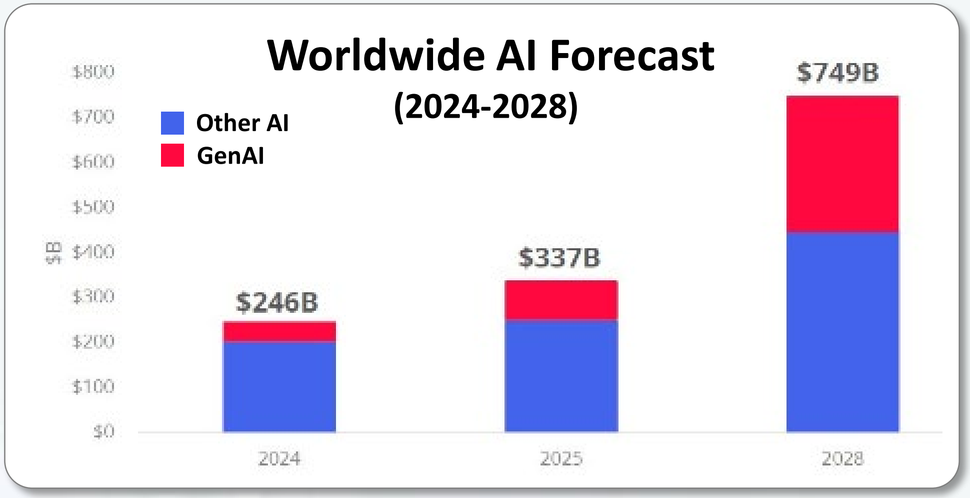
Trillion by 2030

Global GDP

3.5%

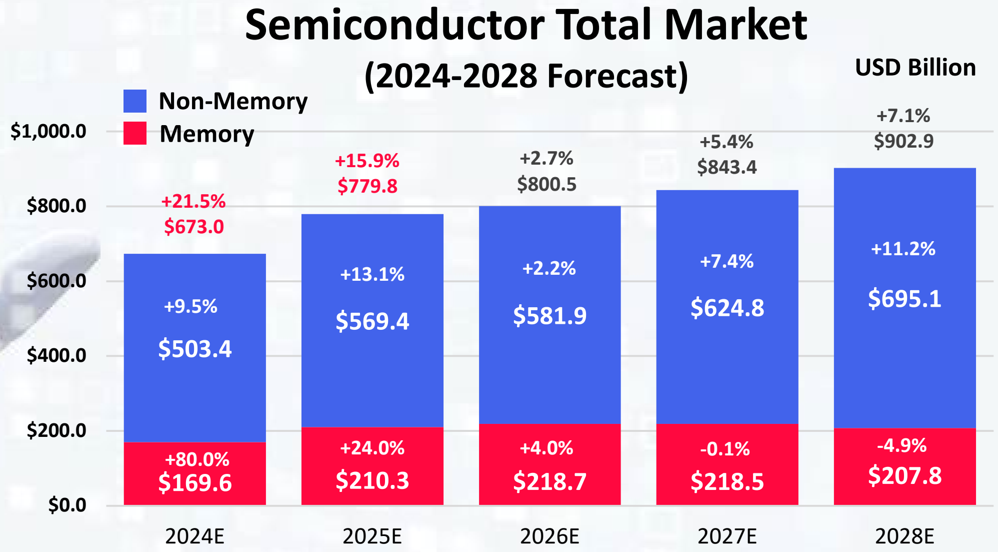


Source : IDC, 2024



Worldwide AI Forecast

(2024-2028)

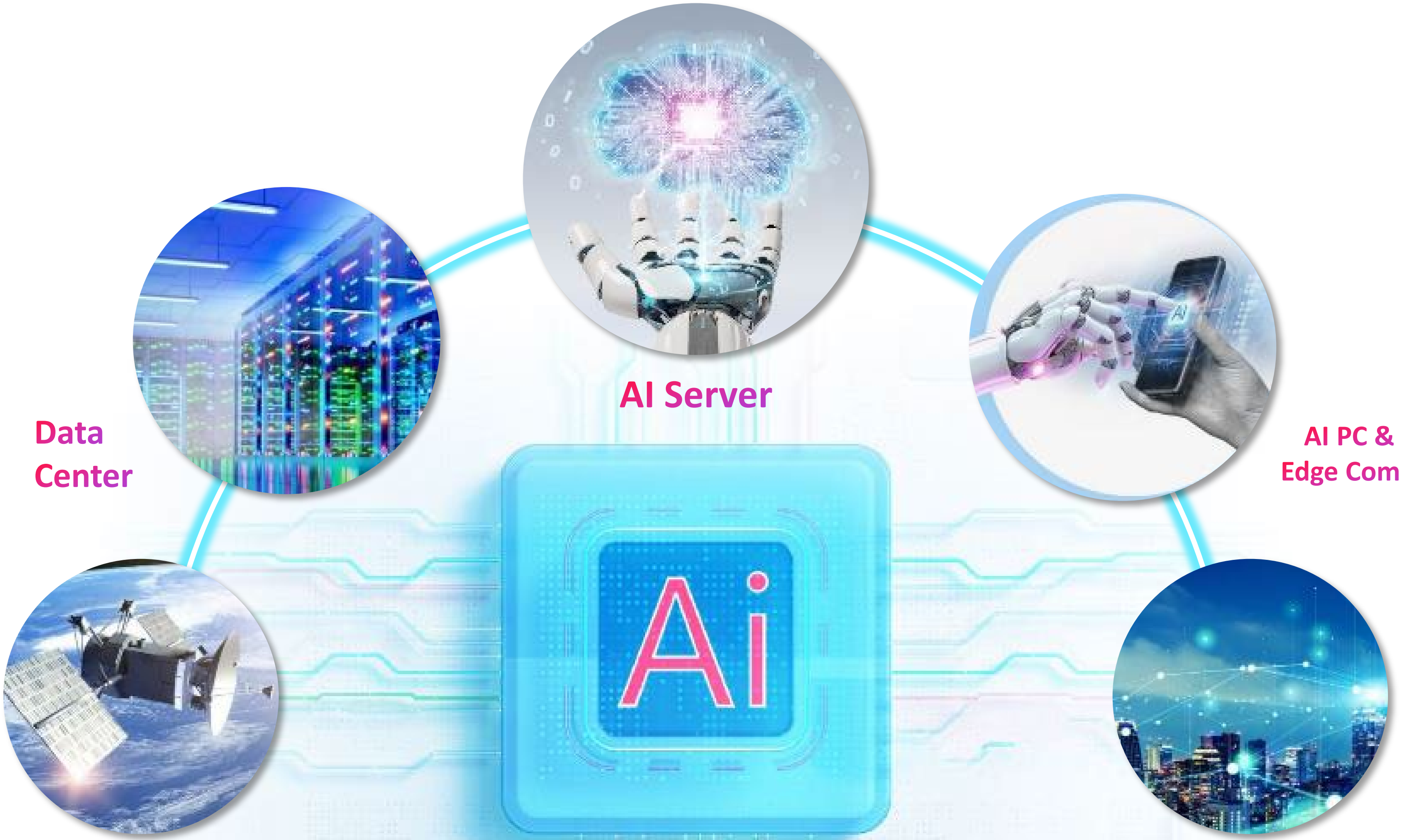


Semiconductor Total Market

(2024-2028 Forecast)

USD Billion

Driving Force for AI



AI Server

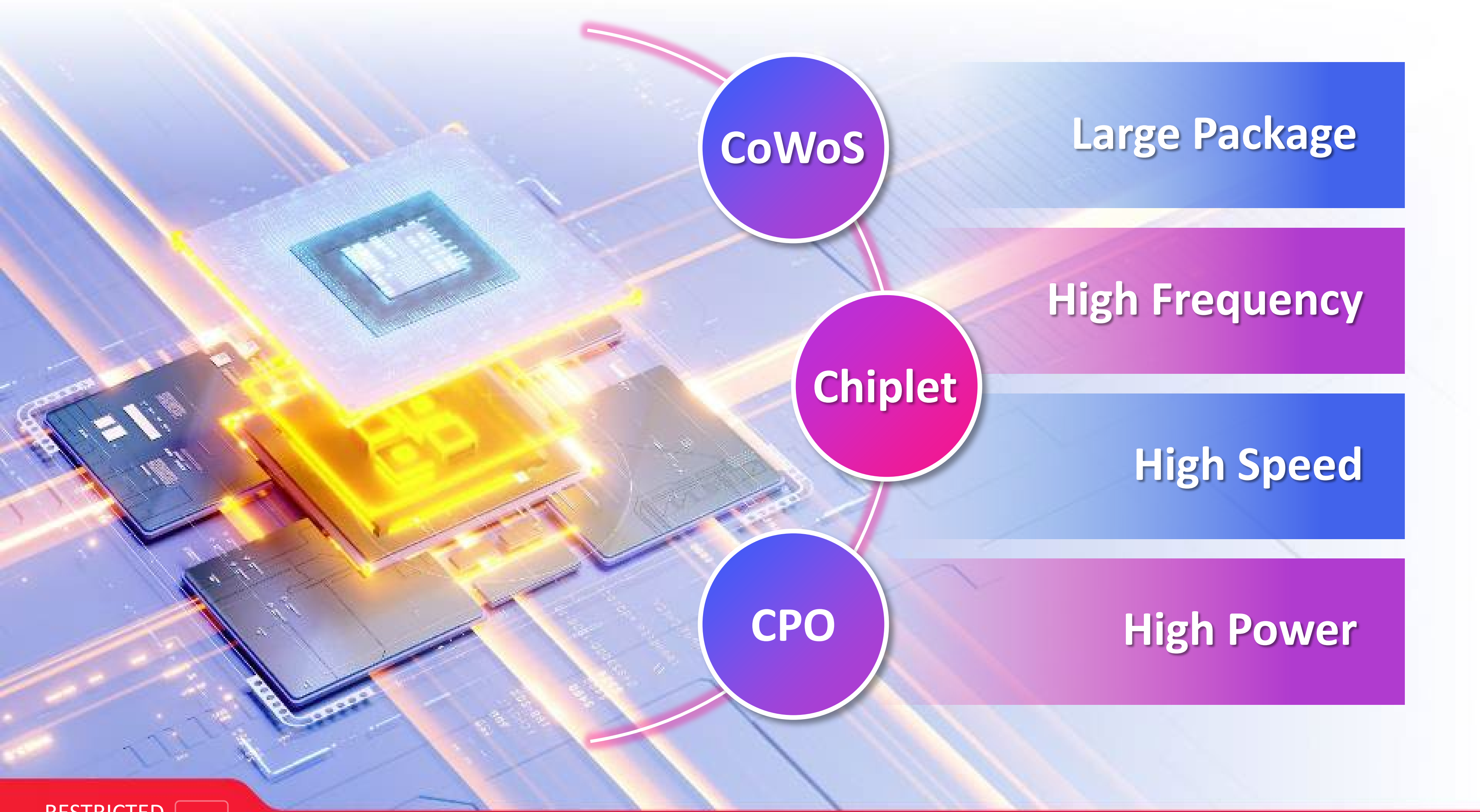
Data Center

AI PC & Phone
Edge Computing

5G&6G Low Earth Orbit Satellite

High Speed
Networking

High Performance Testing Driven by Advanced Packaging



CoWoS

Chiplet

CPO

Large Package

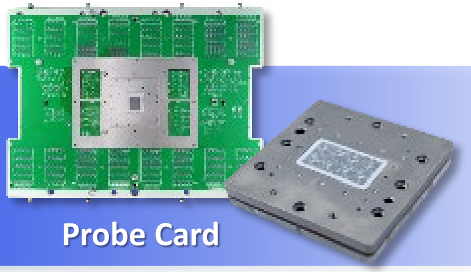
High Frequency

High Speed

High Power

Total Solution for Semiconductor Test

Wafer Sort
(CP - Circuit Probe)

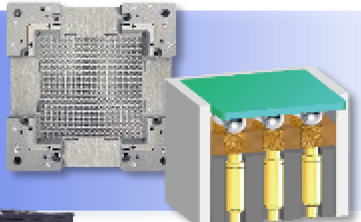

Probe Card

Final Test
(Final Test)


RF & Plastic Socket

SLT (System Level Test)
SFT

Coaxial Socket &
HyperSocket™



Functional Burn-in


Burn-in Socket

DFT **D**esign **F**or **T**esting **DFM** **D**esign **F**or **M**anufacturing

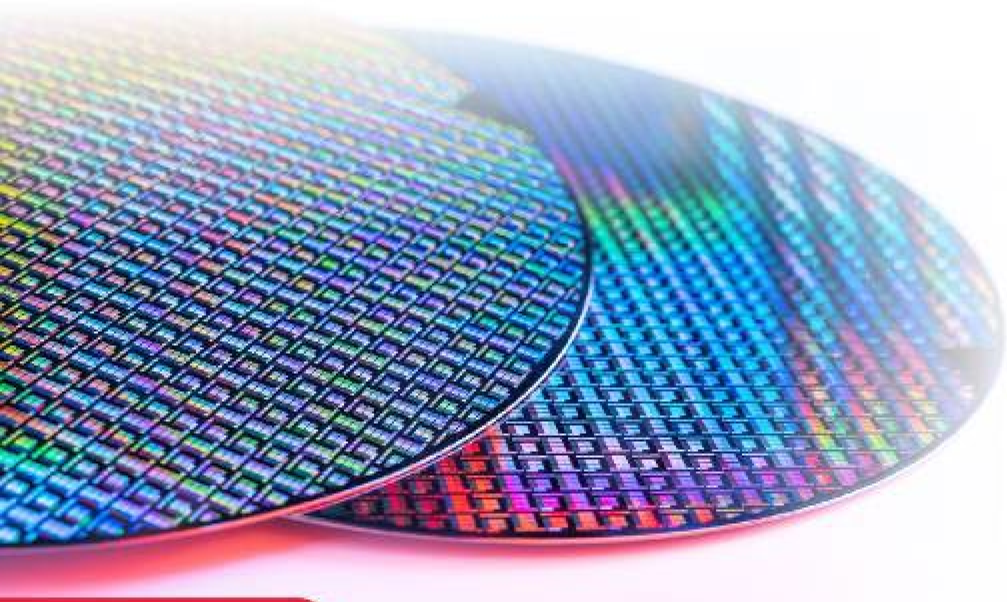
Greater Importance on Chip Probing

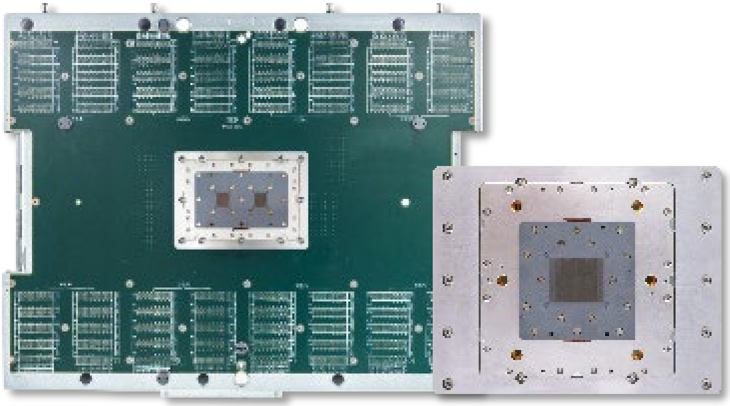
From Shadows to Spotlight

K.G.D

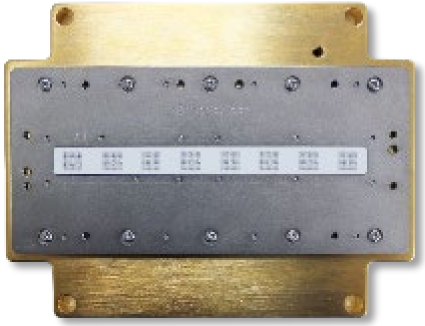
Close to
Known **G**ood **D**ie

- CoWoS
- Chiplet
- CPO





MEMS VPC



WLCSP Probe Card

Cobra VPC

Advanced Packaging Accelerates Demand for System Level Testing

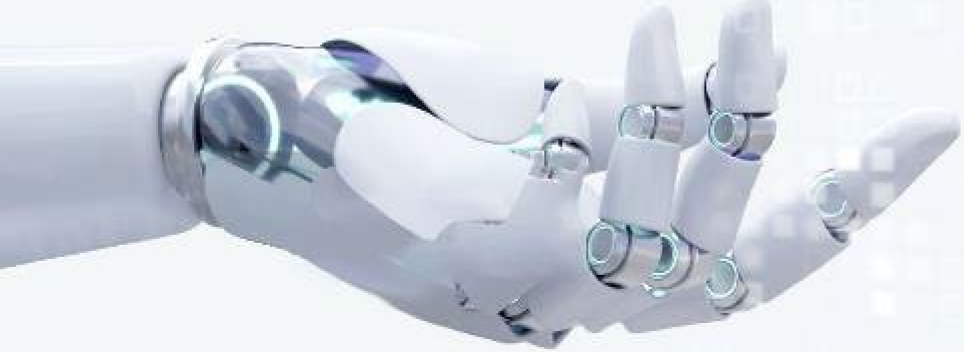
SLT&SFT

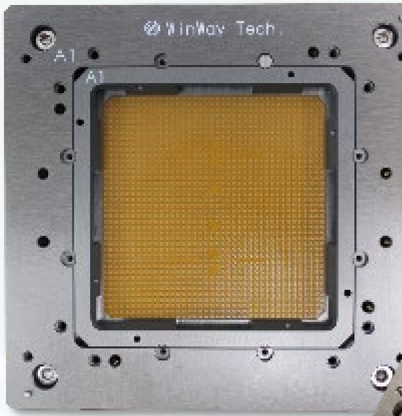
2024-2029 CAGR

More than 15% ↑

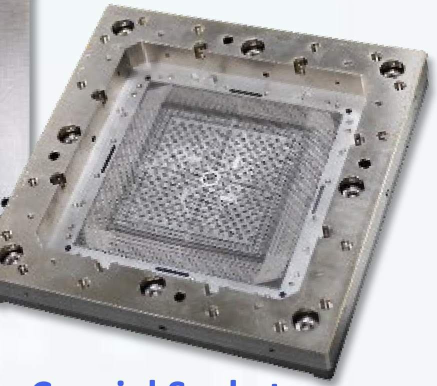
Greater than industry growth

Source : WinWay 2024

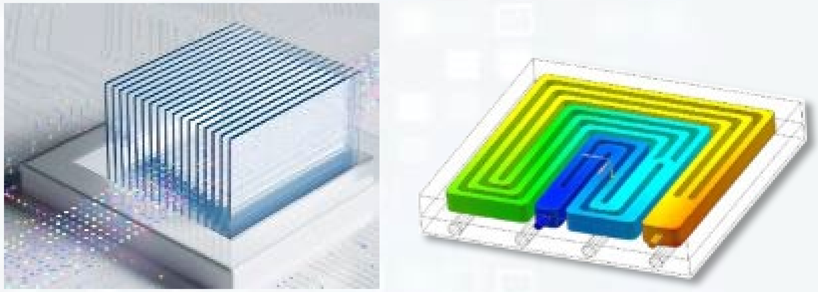




HyperSocket™



Coaxial Socket



Thermal System (Liquid Cooling)

Future Trend for High-Speed Burn-in

Functional Burn-in

- **High Power Burn-In Oven**
- **System Level Test Burn-In**

High Power 1000W

Large Package 120 X 120 mm^2

High Speed PCIE Gen5 32Gbps

Collaborative Robot

Automotive

Data Center

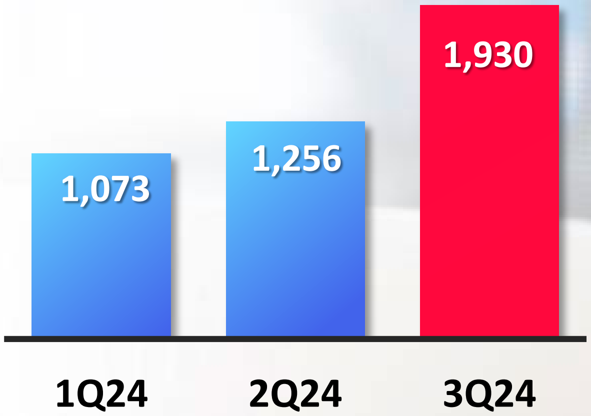
WinWay
穎崴科技

03

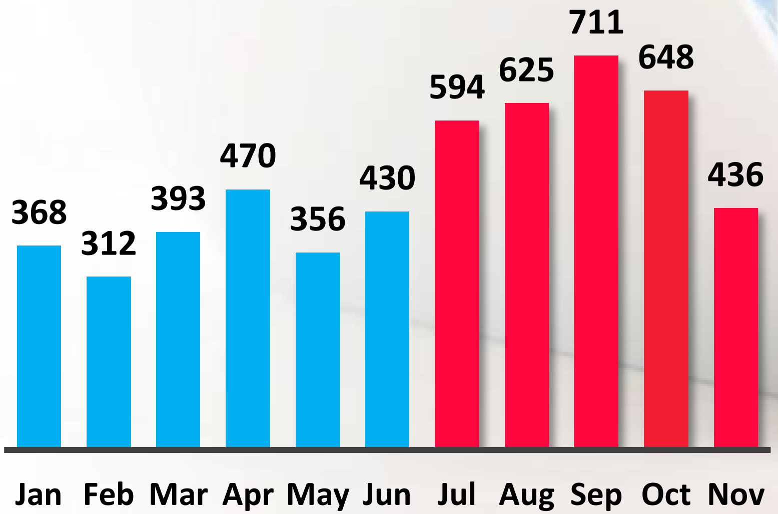
Financial Performance

Revenue Trend

QUARTERLY REVENUE
(NTD MILLION)



MONTHLY REVENUE
(NTD MILLION)



5.3B

YTD
(First 11 Months of 2024)

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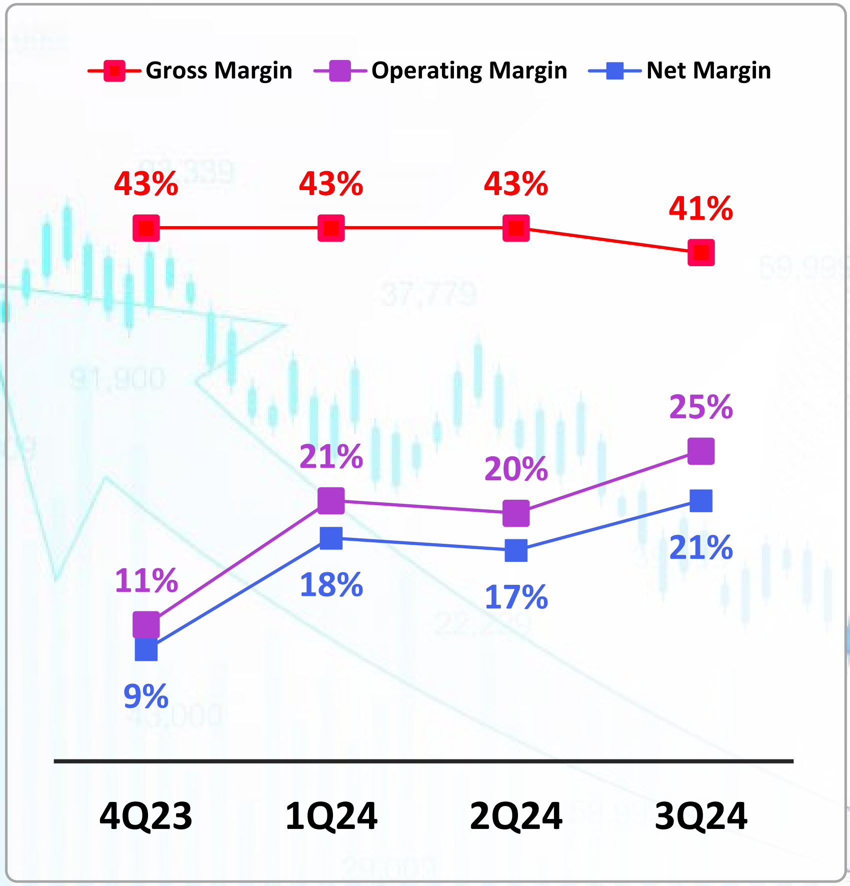
Profitability Trend



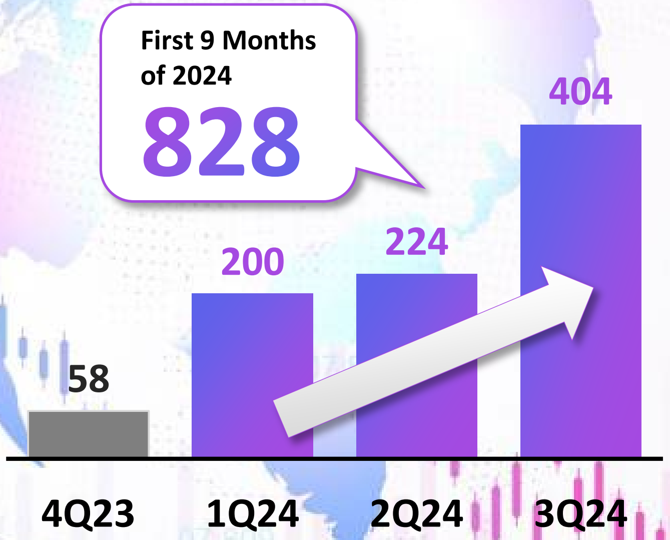
EPS (NT$)

First 9 Months of 2024

24.08

4Q23	1Q24	2Q24	3Q24
1.68	5.81	6.52	11.75

NET INCOME (NTD M)



Revenue by Product Mix

(First 10 Months of 2024)

🟥	Coaxial Socket	49% ↗
🟪	RF & Plastic Socket	22%
🟩	Contact Element	10% ↗
🟧	Probe Card	7% ↗
🟦	Burn-in Socket	5%
⬜	Others	7%

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Revenue by End Market

(First 10 Months of 2024)

HPC & AI

52% ↗

HyperSocket™ , Coaxial

PC & Gaming

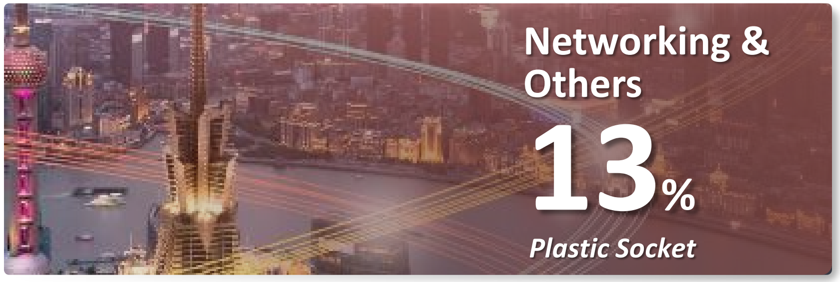
14% ↗

HyperSocket™ , Coaxial

Smart Phone

21%

POP Plastic Socket



Networking & Others

13%

Plastic Socket

WinWay
穎崴科技

04

R&D Innovation

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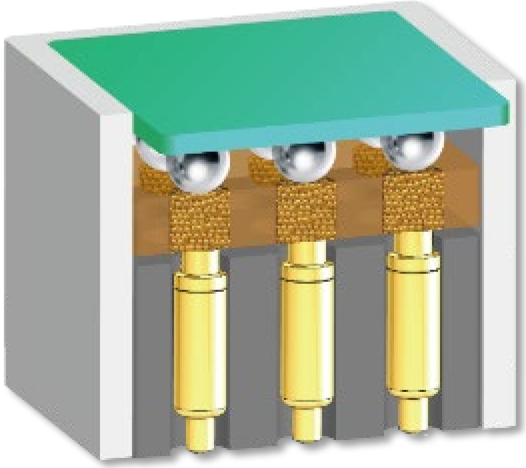
Best-in-Class Test Socket

WinWay HyperSocket™



- Best solution for high-speed signal
- Well-positioned for larger, more advanced package design
- Superior thermal dissipation for high-current testing

Patent NO.

- TWI862047
- TWI862191
- CN20570508U

Patent Pending

- USA
- Japan
- Korea
- Malaysia

Co-Packaged Optics Test Solution

Total Solution for CPO

IC Design

Foundry

OSAT

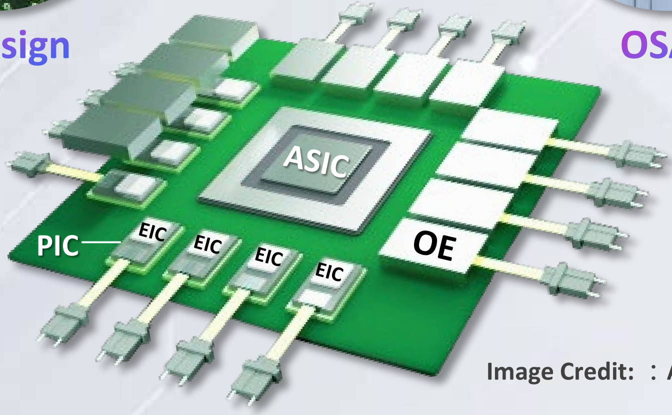
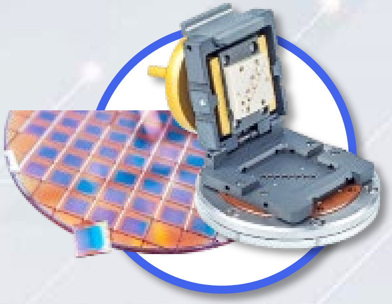


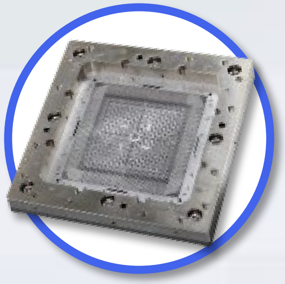
Image Credit: ：ASE

Co-Packaged Optics

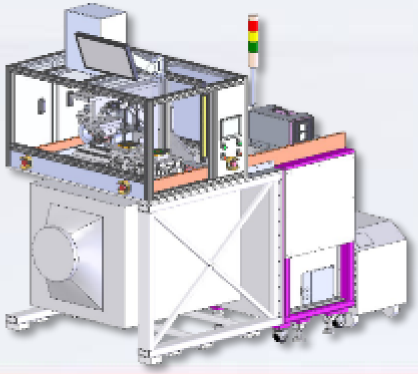


WLCSP Fine Pitch Socket

Optical and Electrical Test Socket



Coaxial Socket



Double Sided Probing System

Spring Probe Manufacturing

Socket All in House

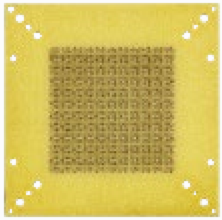
Cost Reduction **Customer Growth**

2025 Demand **8M / Month**

2025 Capacity **4.5M / Month**

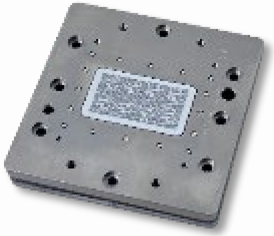
WinWay , We Test !

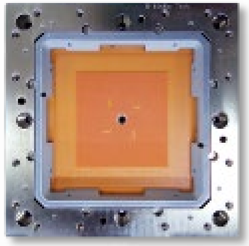

Spring Probe


CRS

Performance

- Application
- Manufacturing
- Design


Probe Card


Coaxial Socket


HyperSocket™

Integration

- IP
- Die
- Package
- Board
- System

Optimization

- Reliability
- Safety
- Security


RF Socket


Burn-in Socket

WinWay 股票代號 6515

THANK YOU

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